| External_Type | Material_Group | Substances | CAS_Number | Mass | Mass_Percentage_in_Leaf | Massmg |
|---|---|---|---|---|---|---|
| Wire | Pure metal | Aluminium (Al) | 7429-90-5 | 0.39 | 100.0 | 19.08522 |
| | | | **Subtotal** | 0.39 | 100 | 19.08522 |
| Die | Doped silicon | Silicon (Si) | 7440-21-3 | 0.43526 | 100.0 | 21.3 |
| | | | **Subtotal** | 0.43526 | 100 | 21.3 |
| Solder Paste | Lead alloy | Tin (Sn) | 7440-31-5 | 0.00102 | 5.0 | 0.05 |
| | Lead alloy | Lead (Pb) | 7439-92-1 | 0.01737 | 85.0 | 0.85 |
| | Lead alloy | Antimony (Sb) | 7440-36-0 | 0.00204 | 10.0 | 0.1 |
| | | | **Subtotal** | 0.02043 | 100 | 1 |
| Wire | Pure metal | Aluminium (Al) | 7429-90-5 | 0.00585 | 100.0 | 0.28628 |
| | | | **Subtotal** | 0.00585 | 100 | 0.28628 |
| Solder Paste | Pure metal | Tin (Sn) | 7440-31-5 | 0.06028 | 5.0 | 2.95 |
| | Pure metal | Silver (Ag) | 7440-22-4 | 0.03014 | 2.5 | 1.475 |
| | Pure metal | Lead (Pb) | 7439-92-1 | 1.11522 | 92.5 | 54.575 |
| | | | **Subtotal** | 1.20564 | 100 | 59 |
| Isolator | Aluminium alloy | Aluminium Trioxide (Al2O3) | 1344-28-1 | 3.8417 | 100.0 | 188 |
| | | | **Subtotal** | 3.8417 | 100 | 188 |
| Lead Frame | Copper alloy | Phosphorous (P) | 7723-14-0 | 0.00515 | 0.03 | 0.252 |
| | Copper alloy | Iron (Fe) | 7439-89-6 | 0.01888 | 0.11 | 0.924 |
| | Copper alloy | Copper (Cu) | 7440-50-8 | 17.13756 | 99.84 | 838.656 |
| | Copper alloy | Silver (Ag) | 7440-22-4 | 0.00343 | 0.02 | 0.168 |
| | Copper alloy | Phosphorous (P) | 7723-14-0 | 0.01642 | 0.03 | 0.8034 |
| | Copper alloy | Iron (Fe) | 7439-89-6 | 0.0602 | 0.11 | 2.9458 |
| | Copper alloy | Copper (Cu) | 7440-50-8 | 54.64713 | 99.86 | 2674.2508 |
| | | | **Subtotal** | 71.88877 | 200 | 3518 |
| Post-plating | Pure metal | Tin (Sn) | 7440-31-5 | 0.0613 | 100.0 | 3 |
| | | | **Subtotal** | 0.0613 | 100 | 3 |
| Mould Compound | polymer | Tetrabromobisphenol A/Epichlorohydrin polymer | 40039-93-8 | 0.35442 | 1.6 | 17.344 |
| | Polymer | Phenol Formaldehyde resin (generic) | 9003-35-4 | 1.43982 | 6.5 | 70.46 |
| | Polymer | Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) | 25928-94-3 | 2.87964 | 13.0 | 140.92 |
| | Filler | Silica fused | 60676-86-0 | 17.27783 | 78.0 | 845.52 |
| | Carbon Black | Carbon black | 1333-86-4 | 0.15506 | 0.7 | 7.588 |
| | Flame retardant | Antimony Trioxide (Sb2O3) - cas no. 1309-64-4 | 1309-64-4 | 0.0443 | 0.2 | 2.168 |
| | | | **Subtotal** | 22.15107 | 100 | 1084 |
| | | | **Total** | 100.00002 | 100 | 4893.6715 |

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